



## Description

### JMT Dual N-channel Enhancement Mode Power MOSFET

#### Features

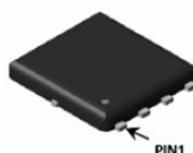
- 40V, 45A
- $R_{DS(ON)} < 9.6\text{m}\Omega$  @  $V_{GS} = 10\text{V}$
- $R_{DS(ON)} < 13.5\text{m}\Omega$  @  $V_{GS} = 4.5\text{V}$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free

#### Applications

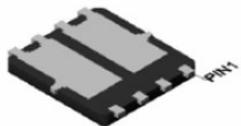
- Load Switch
- PWM Application
- Power Management



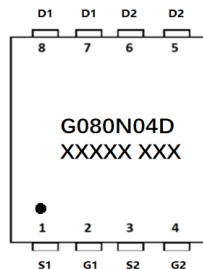
**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**



Top View

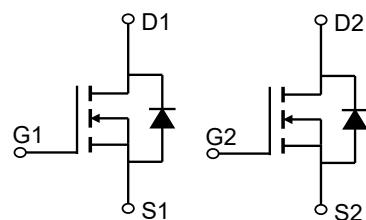


Bottom View



PDFN5x6-8L-D

Marking and Pin Assignment



Schematic Diagram

#### Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
G080N04D	JMTG080N04D	TAPING	PDFN5x6-8L-D	13"	5000	50000

#### Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	40	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current $T_C = 25^\circ\text{C}$	45	A
		28	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	180	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	81	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	25	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	46	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	5	
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

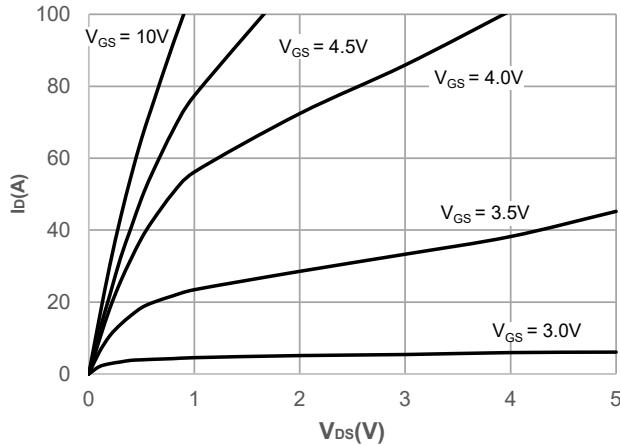
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	40	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.9	2.5	V
$R_{\text{DS(ON)}}$	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10\text{V}, I_D = 30\text{A}$	-	7.4	9.6	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 20\text{A}$	-	10.4	13.5	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 20\text{V}, f = 1\text{MHz}$	-	2443	-	pF
$C_{\text{oss}}$	Output Capacitance		-	167	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	138	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 20\text{V}, I_D = 20\text{A}$	-	48	-	nC
$Q_{gs}$	Gate Source Charge		-	10	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	10	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DD} = 20\text{V}$ $I_D = 20\text{A}, R_{\text{GEN}} = 3\Omega$	-	10	-	ns
$t_r$	Turn-On Rise Time		-	28	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	40	-	ns
$t_f$	Turn-Off Fall Time		-	7	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	45	A	
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	180	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F = 20\text{A}, di/dt = 100\text{A/us}$	-	11	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	5	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

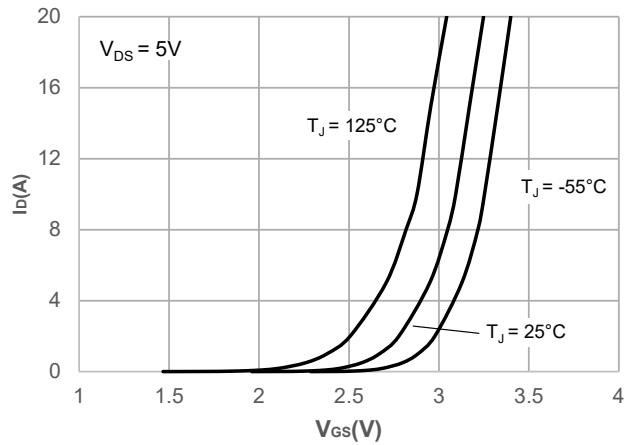
2. E<sub>AS</sub> condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 20\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\text{ohm}$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = 18\text{A}$ 3.  $R_{\theta JA}$  is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB4. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Typical Performance Characteristics

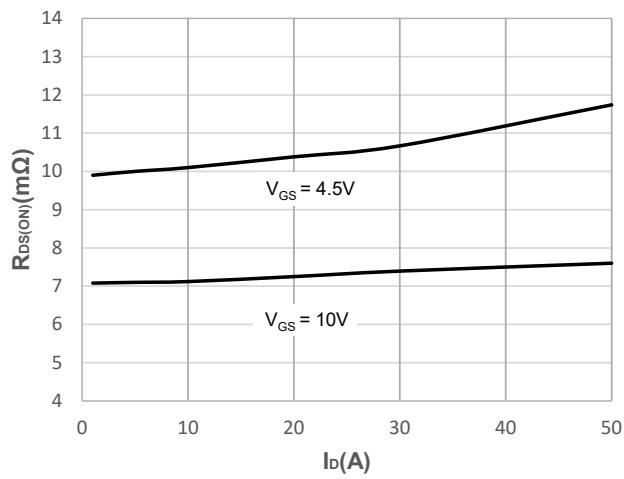
**Figure 1: Output Characteristics**



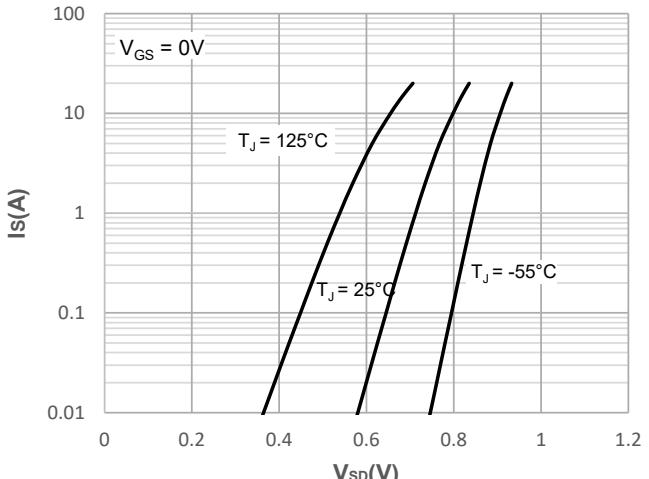
**Figure 2: Typical Transfer Characteristics**



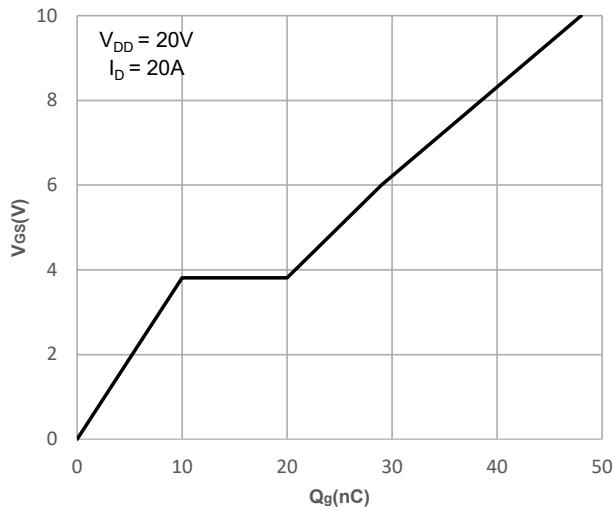
**Figure 3: On-resistance vs. Drain Current**



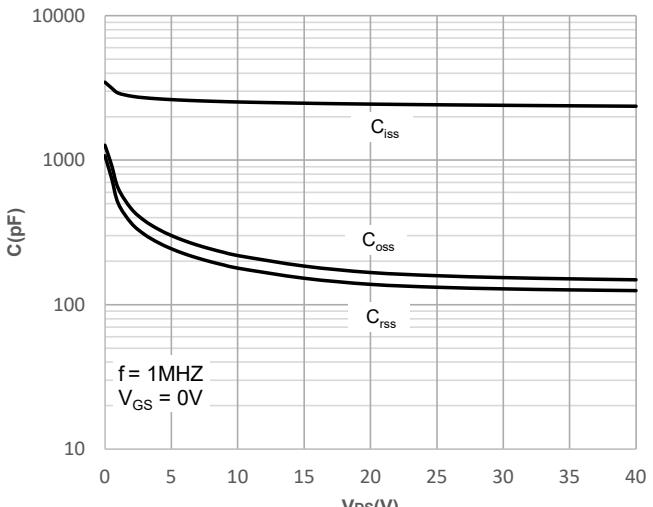
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

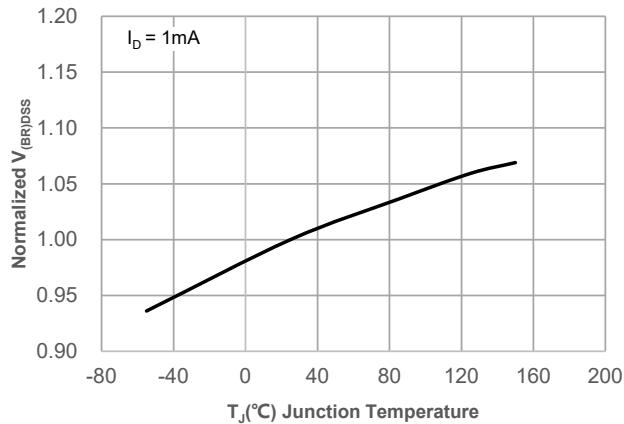


**Figure 6: Capacitance Characteristics**

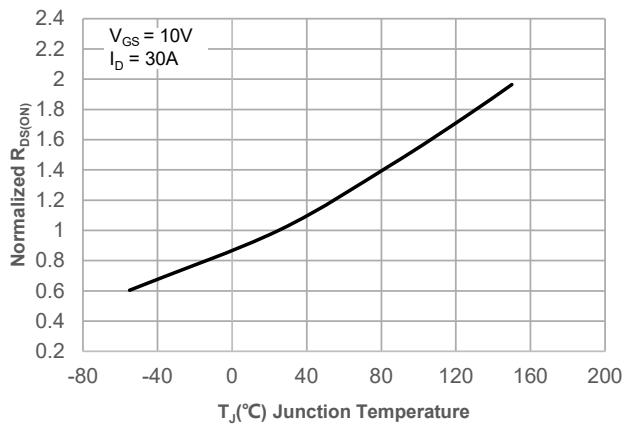


## Typical Performance Characteristics

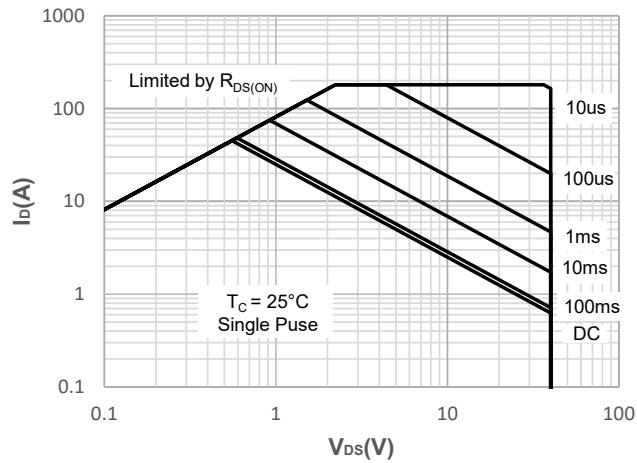
**Figure 7: Normalized Breakdown voltage vs. Junction Temperature**



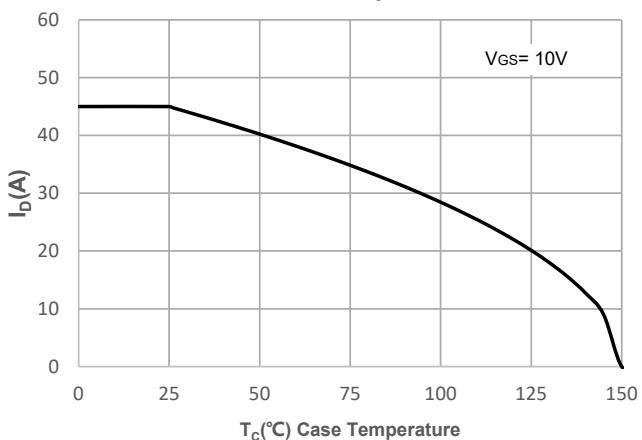
**Figure 8: Normalized on Resistance vs. Junction Temperature**



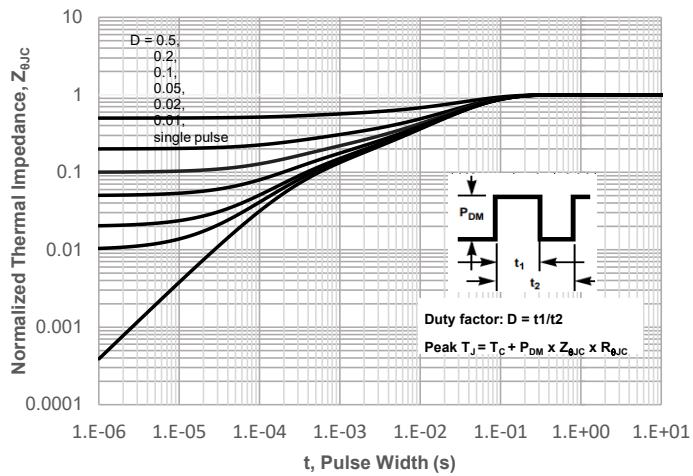
**Figure 9: Maximum Safe Operating Area**



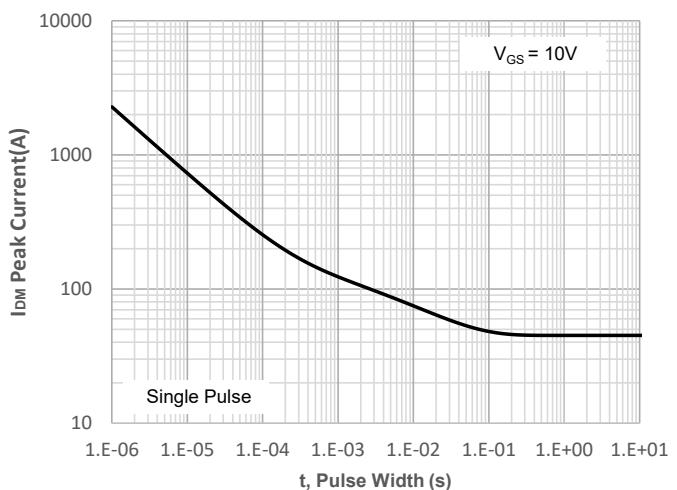
**Figure 10: Maximum Continuous Drian Current vs. Case Temperature**



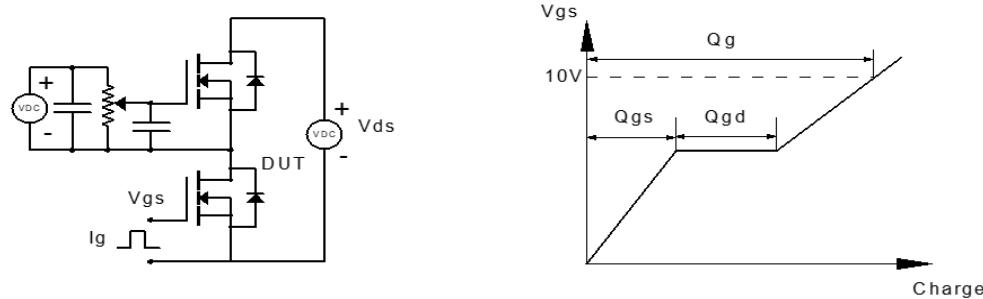
**Figure 11: Normalized Maximum Transient Thermal Impedance**



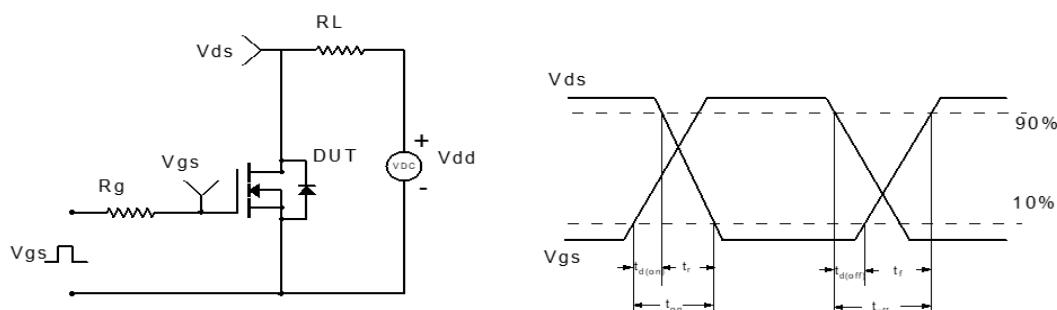
**Figure 12: Peak Current Capacity**



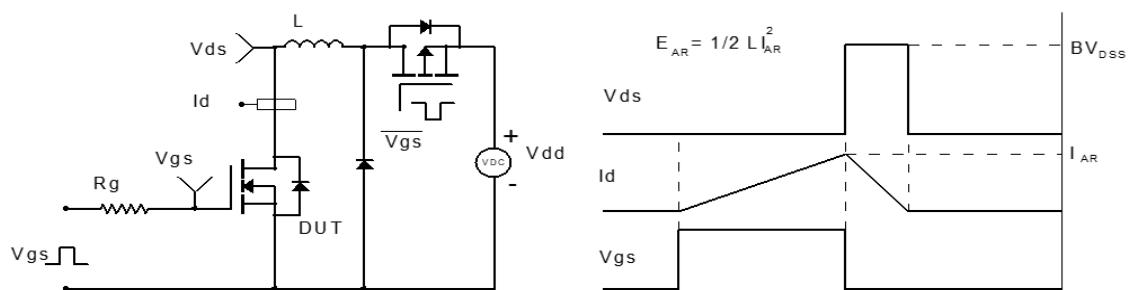
## Test Circuit



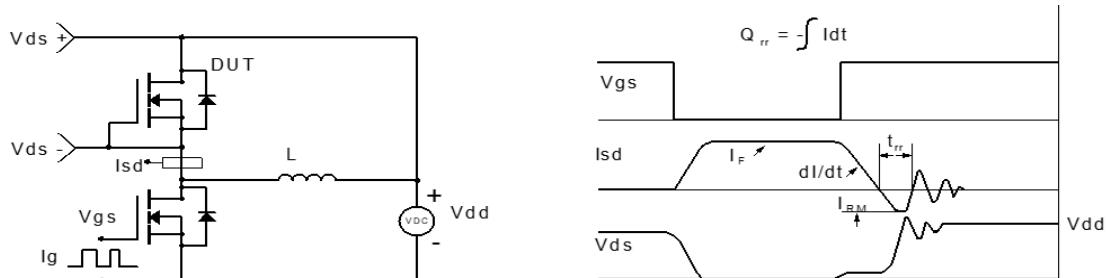
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

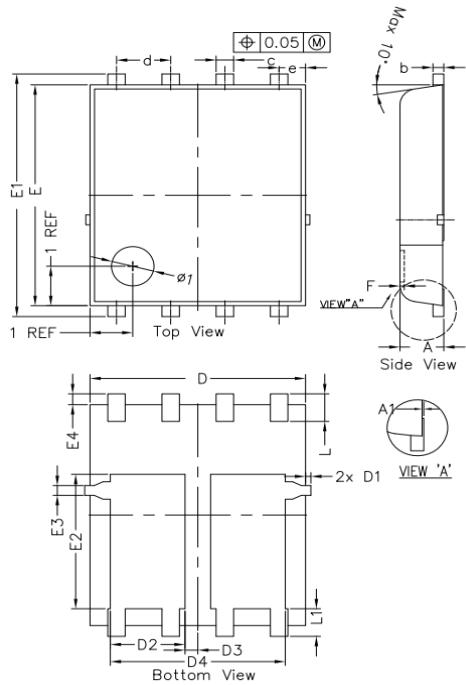


**Figure 3: Unclamped Inductive Switching Test Circuit& Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

## Package Mechanical Data(PDFN5x6-8L-D)



SYMBOLS	DIMENSION IN MM			DIMENSION IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
* A	0.900	1.000	1.100	0.035	0.039	0.043
A1	0.000	---	0.050	0.000	----	0.002
b	0.246	0.254	0.312	0.010	0.010	0.012
* c	0.310	0.410	0.510	0.012	0.016	0.020
d	1.27 BSC			0.050 BSC		
* D	4.950	5.050	5.150	0.195	0.199	0.203
* D1	---	---	0.125	---	---	0.005
* D2	1.650	1.750	1.850	0.065	0.069	0.073
D3	0.200	0.300	0.400	0.008	0.012	0.016
D4	4.000	4.100	4.200	0.157	0.161	0.165
e	0.62 BSC			0.024 BSC		
* E	5.500	5.600	5.700	0.217	0.220	0.224
* E1	6.050	6.150	6.250	0.238	0.242	0.246
E2	3.310	3.410	3.510	0.130	0.134	0.138
E3	0.150	0.250	0.350	0.006	0.010	0.014
* E4	0.175	0.275	0.375	0.007	0.011	0.015
F	-	-	0.100	-	-	0.004
* L	0.500	0.600	0.700	0.02	0.02	0.03
L1	0.600	0.700	0.800	0.02	0.03	0.03

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